

Page 11, replace the first full paragraph as follows:

as
--The method may further include the step of (h) adhering a reinforcing plate on a first surface of the flexible printed circuit sheet across a width of the flexible printed circuit sheet, the step (h) being carried out prior to the step (d).--

IN THE CLAIMS:

Amend claim 1 as follows:

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--1. (amended) A signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of said signal processing circuit substrate, said device having a variable value and including an value adjustment portion through which said variable value is adjusted,

said signal processing circuit substrate including a mounting member to which said device is electrically and mechanically connected such that said value adjustment portion faces a through-hole formed throughout said signal processing circuit substrate,

said mounting member being fixed at opposite edges thereof onto said first surface of said signal processing circuit substrate.--

Amend claim 20 as follows:

--20. (amended) A signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of said signal processing circuit substrate, said device having a variable value and including an value adjustment portion through which said variable value is adjusted,

said signal processing circuit substrate being formed with a through-hole,

said signal processing circuit substrate including a flexible arch-shaped member having a height relative to said first surface of said signal processing circuit substrate,

a) said device being electrically and mechanically fixed onto a lower surface of said member in a floating condition above said signal processing circuit substrate such that said value adjustment portion is in alignment with said through-hole so as to allow said value adjustment portion to be adjusted through said through-hole,

said member being fixed at opposite edges onto said first surface of said signal processing circuit substrate.--

Amend claim 40 as follows:

a8 --40. (amended) A method of fabricating a signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of said signal processing circuit substrate, said device having a variable value

and including an value adjustment portion through which said variable value is adjusted,

said method comprising the sequential steps of:

(a) mounting said device onto an upper surface of a flexible member such that said value adjustment portion upwardly faces;

(b) bending said flexible member at first lines thereof towards said lower surface;

(c) bending said flexible member at second lines towards said upper surface, said second lines being located between said device and said first lines; and

(d) fixing said flexible member at its opposite ends onto said first surface of said signal processing circuit substrate such that said value adjustment portion is exposed through a through-hole formed through said signal processing circuit substrate, wherein,

the method steps produce a signal processing circuit substrate for a liquid crystal display unit with the variable value device mounted on the first surface of said signal processing circuit substrate.--

af
and
(Amend claim 41 as follows:]

--41. (amended) The method as set forth in claim 40, further comprising the step of (e) fixing a reinforcing plate

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cont onto a lower surface of said flexible member, said step (e) being carried out before said step (d).--

Amend claim 47 as follows:

99 --47. (amended) A method of fabricating a signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of said signal processing circuit substrate, said device having a variable value and including an value adjustment portion through which said variable value is adjusted,

said method comprising the sequential steps of:

(a) patterning a flexible printed circuit sheet into patterns which will make flexible printed circuits;

(b) covering said flexible printed circuit sheet with an electrical insulator;

(c) mounting said device on a second surface of said flexible printed circuit sheet;

(d) cutting said flexible printed circuit sheet into flexible printed circuits;

(e) downwardly bending said flexible printed circuit sheet at first lines across said device;

(f) upwardly bending said flexible printed circuit sheet at second lines across said device, said second lines being located between said device and said first lines; and